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(54) Title: STORAGE STABLE COMPATIBLE CURING AGENT COMPOSITIONS FOR EPOXY RESINS SELF CURABLE AT SUB-AMBIENT TEMPERATURES (57) Abstract There is provided a curing agent composition for epoxy resins and two component curable epoxy resin compositions. The curing agent is made by reacting at least a b) substituted aryl amidopolyamine with a c) monoglycidyl capping agent, where the substituted aryl amidopolyamine is made by reacting at least; bi) a phenolic compound substituted with at least one carboxyl group and at least one hydrocarbyl group having at least 1 carbon atom, and bii) an aliphatic polyamine compound having at least two primary amine groups. The curing agent is storage stable for at least 6 months. There is also provided a two component epoxy resin composition, which advantageously can be made in the absence of external catalysts/accelerators, and can cure within 24 hours at the low temperature of 4.4 °C. The two component epoxy resin composition also exhibits excellent compatibility between the curing agent and the epoxy resin, thus reducing or eliminating the need for an induction time.		